



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Guoqiang Xing, et al.

Docket No: TI-31729

Serial No: 09/901,416

Conf. No: 7364

Examiner: Thanh T. Nguyen

Art Unit: 2813

Filed: 07/09/2001

For: DUAL HARDMASK PROCESS FOR THE FORMATION OF COPPER/LOW-K INTERCONNECTS

**NOTICE OF APPEAL FROM THE PRIMARY EXAMINER
TO THE BOARD OF APPEALS**

Mail Stop AF
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on 6-18-03.

Ann Trent
Ann Trent

Dear Sir:

Applicants hereby appeal to the Board of Appeals from the decision of the Primary Examiner mailed March 24, 2003, finally rejecting Claims 1-13.

The item(s) checked below are appropriate:

1. ☐ An extension of time to respond to the final rejection
☐ was granted on _____.
☐ is requested for ____ month.
2. ☒ A timely response to the final rejection has been filed.
3. ☒ Fee \$320.00:

☐ Not required (Fee paid in prior appeal)

☒ The Commissioner of Patents is hereby authorized to charge any fees which may be required or credit any overpayment to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

This form is submitted in triplicate.

06/25/2003 DTESSEM1 00000161 200668 09901416

01 FC:1401 320.00 DA

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AF 72800
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to
Appeal
7-10-03

RECEIVED
JUN 25 2003
TECHNOLOGY CENTER 2800